



The European Institute for the PCB Community

EIPC NEWS

A headline in a Sunday newspaper caught the eye – “Now, more than ever, we need to talk”.

Better communication with colleagues can help in these turbulent times. Manufacturing industry continues, in spite of all the obstacles, and the need to keep informed has not lessened. Thus it is that EIPC have decided to run another technical webinar, and this will be held on 20th January 2021 at 15:00 hours CET.

There will again be three speakers, and the opportunity to have your questions answered before the conclusion.

Moderated by our Chairman Alun Morgan, we will hear initially from **Walt Custer**, who needs no introduction. In a 40-minute presentation, Walt will provide a Business Outlook for the Global Electronics Industry – with the emphasis on Europe.

From **AT&S** In Austria, **Herr Erich Schläffer** will, over 15 minutes, hold up for inspection 5GmmWave which is a fundamental transformation in the Packaging & Substrate world with a high impact to existing PCB interconnection technology.

From **Taiyo** the always affable **Don Monn** will devote quarter of an hour to show how we may finally capture the holy grail of solder mask. The next step is right in front of us all – we just need the courage to take the step that is presenting itself. Don will explain all.

Abstract: Soldermask is a necessity that has been around for a very long time. It has evolved several times over the decades and continues its evolution even today. We’ve been updated on the current growth of Inkjet Soldermask, but how did we get to this point? Today we will see and hear how Soldermask has changed to meet the growing demands

over the past 4 decades. Who is driving these changes and where will it all lead? When will we finally capture the holy grail of Soldermask, or will we ever? The next step is right in front of us all. We just need the courage to take the step that is presenting itself.

There will be a Q&A session after the last speaker.

For EIPC members the webinar is free of charge; for non-members the fee will be € 50,-.

To register online, please go to www.eipc.org



The European Institute for the PCB Community

EIPC SPEeDNEWS

*The Weekly On-Line Newsletter from the European Institute of Printed Circuits.
Issue 2 – January 2021*

NEWS FROM BELGIUM

Rogers Corporation's Advanced Connectivity Solutions Business adds EMEA Distribution Channel

Partnership enhances Rogers' ability to service RF and low-loss PCB customers

Rogers Corporation's (NYSE:ROG) Advanced Connectivity Solutions (ACS) business unit have announced the introduction of a new distribution channel with the addition of CCI Eurolam (CCI) to their sales and service team in the EMEA effective January 1st, 2021.

ACS provides global customers with market-leading high performance and high reliability RF material solutions. CCI comes with over 50 years of sales and service experience in PCB processing and materials distribution. Rogers ACS' continued expansion in the EMEA, combined with CCI's extensive experience and distribution network, will provide the highest level of support to customers. Rogers and CCI, working closely as a team, will provide both sales and onsite service/support to PCB manufacturing customers throughout the EMEA.

Dirk Lefelon, ACS Sales Manager Europe, noted, "I am pleased CCI and Rogers were able to form this relationship that focuses on enhancing our ability to service our customers in EMEA through improved service and local support."

Rogers Corporation (NYSE:ROG) is a global leader in engineered materials to power, protect, and connect our world. With more than 180 years of materials science experience, Rogers delivers highperformance solutions that enable the company's growth drivers-- advanced connectivity and advanced mobility applications, as well as other technologies where reliability is critical. Rogers delivers Power Electronics Solutions for energy-efficient motor drives, e-Mobility and renewable energy; Elastomeric Material Solutions for sealing, vibration management and impact protection in mobile devices, transportation interiors, industrial equipment and performance apparel; and Advanced Connectivity Solutions for wireless infrastructure, automotive safety and radar systems. Headquartered in Arizona (USA), Rogers operates manufacturing facilities in the United States, China, Germany, Belgium, Hungary, and South Korea, with joint ventures and sales offices worldwide.

CCI Eurolam is based in France, United Kingdom and Germany and provides EMEA supply chain coverage with 3 stocking locations. Founded in 1968, CCI has grown to its present size by serving the needs of the printed circuit industry as a market leading distributor of specialty materials, chemistries and equipment. CCI is recognized as a market leader in the

PCB industry through the strong partnerships forged with customers and suppliers, and its dedication to service,



The European Institute for the PCB Community

EIPC SPEeDNEWS

*The Weekly On-Line Newsletter from the European Institute of Printed Circuits.
Issue 2 – January 2021*

NEWS FROM CANADA

Ventec Strengthens Canada OEM Activities with Appointment of Sigma Component Design

Ventec International Group Co., Ltd. (6672 TT) today announced the appointment of Sigma Component Design (Sigma) to provide sales and support to OEM customers in Canada. The two companies have signed a contractual agreement under which Sigma will help drive new OEM business for Ventec in Canada and represent all product lines from 1st January 2021.

The Canadian market is experiencing significant growth in demand from OEM customers mainly from the ICT industries and also for automotive, medical, aerospace & defence, and other applications.

As part of Ventec's global growth strategy and to support its sales activities in Canada, Ventec has appointed Sigma due to its excellent OEM focused sales organization, local presence, market knowledge and exceptional reputation.

"Sigma Component Design will be a great asset to support and grow our existing OEM customer base in Canada. We look forward to their contribution and ability to secure new clients in the region," stated Chris Hanson, Global Head IMS Technology at Ventec.

John Grobanopoulos, President & Owner of Sigma added "We are excited to be working in partnership with Ventec. We believe the quality and reliability of Ventec's high performance PCB base material solutions will resonate with the needs of our OEM customers in Canada. Our agreement with Ventec is synergistic with our leading market access and full range of other solutions. We look forward to helping Ventec expand their reach and working together to help bring additional value to our customers across the region."

Ventec International is a world leader in the production of polyimide & high reliability epoxy laminates and prepregs and specialist provider of thermal management and IMS solutions. Further information about Ventec's solutions and the company's wide variety of products is available at www.venteclaminates.com and/or by downloading the Ventec APP.



The European Institute for the PCB Community

EIPC SPEeDNEWS

*The Weekly On-Line Newsletter from the European Institute of Printed Circuits.
Issue 2 – January 2021*

NEWS FROM GERMANY

Sensry and MST Group Enter Strategic Long-Term Cooperation

Sensry GmbH (Sensry) and Micro Systems Technologies (MST Group) announced today the entering of a strategic long-term cooperation using synergies between and interests of both companies to grow together in the Internet-of-Things (IoT) market.

Sensry and MSTGroup intend to cooperate in the areas of semi-conductor systems design, development, assembly, interconnect, packaging, SMT processes and electrical test of IoT solutions developed by Sensry.

The packaging needs inherent in the Sensry business model with a universal sensor platform solution kit are widely covered by the service offer and philosophy of the MSTGroup.

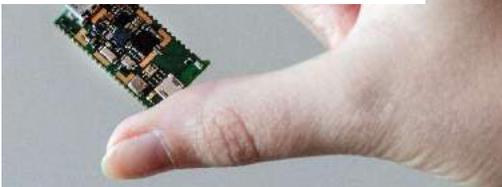
“We are proud to have MST Group as development partner and volume manufacturing supplier for our highly flexible IoT solutions for our customers. As we are specialized to build customized solutions with multiple sensors, communication concepts and form factors based on leading edge technologies, the MSTGroup is a perfect addition to our manufacturing network.”, said Konrad Herre, CEO of Sensry, and added speaking for both partners: “With our cooperation we support the growth of Semiconductor Industry and the related Supply Chain in Europe, by easing customer access to the IoT market field, shortening time-to-market, and offering “Security Made in Germany” products at reasonable prices.”

Christian Rössle, President Sales & Marketing of MSTGroup, commented: “We are delighted to join forces with Sensry and to offer our “One-Stop-Service” capabilities to IoT module customers, in many different industries, from our high-end semiconductor packaging facility in Berg, Germany. Our partnership approach comprises semiconductor packaging based on our inhouse PCB and IC-Substrate manufacturing, and electrical test services, joint package development projects from samples to volume manufacturing, the programming and calibration of sensors, logistics for wafer, chip, component, and sub-assembly storage, marking, labeling, packing and drop-shipment to Sensry customers.”

sensry kallisto®



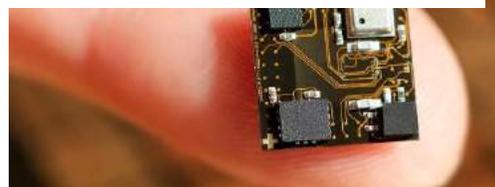
©Fraunhofer Portugal, AICOS



sensry ganymed®



©Fraunhofer Project USeP



Company Profiles

Sensry supports customers with sensor and sensor fusion nodes developing customized high integrated modular systems of sensors, powerful computing and control units and communication interfaces. The system components are based on the latest technologies and manufactured in cooperation with market leaders for volume production and are supported with software development kits (SDK). Sensry got established in November 2018 in Dresden, Germany, one of the Microelectronics Centers in Europe, and has a cooperation with several Fraunhofer institutes for development and GLOBALFOUNDRIES for production.

Sensry offers currently two platforms, "*Sensry Kallisto*", currently entering the market and ramping, and "*Sensry Ganymed*", which is in its final development phase to be shipped begin of 2021, both supporting customer applications based on their modularity and performance.

Sensry - Key Competences:

- Provision of platforms for "All Integrated Smart & Secure Sensors",
- Design and development of flexible universal leading-edge IoT applications with:
 - Integration of multiple various sensors,
 - Support of multiple communication standards,
 - Low power consumption,
 - High performance processors for smart node computing,
 - Inherent multi-layer data security and authentication,
 - Adequate memory resources,
- Access for SME to leading edge technology solutions typically not affordable,
- Enabling the "Democratization of Digitalization" in the industry and our lives,
- Very fast design using standard library hardware chiplets,
- Customized module configuration with short lead time,
- Smallest form-factor due to advanced packaging concepts,
- Complete supply chain support and management,
- Prototyping, testing, ramp-up and production support, scaling to high volume,
- Software and systems support (SDK, driver, security systems, services),
- Wireless API support for user comfort and acceptance.

MST Group provides innovative products and services for high-tech industries, which require exceptional performance, highest quality, and reliability such as medical, aerospace, telecommunication, and demanding applications in the field of sensors and actuators. The company acts internationally with more than 1,100 employees in three countries, which are providing integrated solutions to their customers from concept to volume production, specialized on small and medium sized manufacturing volumes.

MST Group - Key Competences in the field of semiconductor packaging technology:

- Customer specific packaging solutions applying a wide range of materials, form-factors, and package configurations, hermetic and non-hermetic,
- Integrated packaging solutions from concept to volume production (specification, design, prototyping, volume manufacturing of market-ready products),
- Inhouse manufacturing of organic and ceramic IC-Substrates and PCBs,
- A wide range of advanced System-in-Package (SiP) and board-assembly technologies,
- Flexible manufacturing infrastructure, cost-efficient production of prototypes and volume production of small and medium-sized volumes under one roof,

- Uncompromising quality policy, certified ISO 9001 and ISO 13485, and in line with relevant industry specific standards,
- Complete traceability of materials and processes,
- Sustainable development programs, continuous improvement of processes, strategic partnerships, experienced and competent employees.

- **Media contacts**

Sensry

Konrad Herre

k.herre@sensry.de

Phone +49 160 714 90 90

www.sensry.de

MSTGroup

Christian Rössle

christian.roessle@mst.com

Phone +49 30 68905 4060

www.mst.com



The European Institute for the PCB Community

EIPC SPEeDNEWS

*The Weekly On-Line Newsletter from the European Institute of Printed Circuits.
Issue 2 – January 2021*

NEWS FROM THE UK

IFS2021 Registrations Now Open

Future Horizons' Annual Semiconductor Industry Outlook & Forecast.

When? Tue 19 January 2021 - 3 pm GMT / 7 am PST / 10am EST / 11 pm JST

Where? https://us02web.zoom.us/webinar/register/6716088077353/WN_OFksqKNDTMujGAT-T24Kdw

Why? Covid-19 may have pummeled 2020 GDP growth yet the semiconductor market grew an impressive 7 percent. Not only that, this strong growth has continued unabated throughout the seasonally weak fourth quarter. Tight chip capacity and strong end user demand has sent manufacturers scrambling for supply, firing the starting gun for the next semiconductor industry super-cycle. Despite these positives, the cold wind of global economic uncertainty hangs like the sword of Damocles over the industry. Find out more how these factors are will play out and what the likely growth outcome will be. Also to be covered are the key application and technology trends.

Now in its 33rd, Future Horizons is committed, more than ever, to providing you with high quality, cost-effective market research and analysis to help semiconductor leaders prepare themselves for the next normal. We are not afraid to stick our necks out and go against the tide to ensure you get the right information, and this event will be no exception. Our proven deep insights makes IFS2021 a must-attend event for any leader within the semiconductor, electronics and related industries.

Will the current semiconductor growth fizzle out or continue?
Find out at Future Horizons' 2021 Annual Industry Webinar:

https://us02web.zoom.us/webinar/register/6716088077353/WN_OFksqKNDTMujGAT-T24Kdw

Who Should Attend?

- Key decision-makers engaged in the design, fabrication or supply of semiconductors

- Senior marketing executives planning a post COVID marketing strategy
- Those involved in investing or banking within the electronics industry
- Government organisations involved in trade and investment

Why Future Horizons?

We have been in the business of forecasting and analysing the semiconductor market for over 50 years and have been a trusted advisor to governments, investors and most of the top global semiconductor firms. Time and time again we have delivered sound advice and saved our clients time and money with our forensic and accurate analysis of the industry.

Book Your Seat Today (Spaces are limited)

Go to: https://us02web.zoom.us/webinar/register/6716088077353/WN_OFksqKNDTMujGAT-T24Kdw

- For a small investment of £95 plus tax you will gain accurate industry insight to make good strategic decisions in these uncertain times
- Discount available for 3 or more attendees from the same company/organisation
- Webinar can also be held in-house for your added convenience and flexibility
- Please pass to a colleague if already attended or not suitable for you

Malcolm Penn
Chairman & CEO

Twitter

Follow us on Twitter, like us on Facebook and join our Linked In Group and receive regular industry news, information and comments.
Registered Company: 4380991



"Semiconductor Packaging Workshop"

"Includes Packaging Surgery to Answer Those Thorny Issues"

Thursday 11 February 2021: 10:00 - 16:00

This **Online Workshop** provides training for staff who need to be aware of the benefits of employing **basic packaging technologies** for the **design, manufacture and test of electronic products**. It will also serve as a refresher for those who wish to expand the breadth of their knowledge in:

- Die Preparation, Attach and Interconnection Techniques
- Package, Substrate and Encapsulation Options
- Modelling and Simulation
- Test, Inspection and Reliability

Register below for this event.

[Register Here](#)

Forthcoming IMAPS-UK Online Events

Please Click on the Links below for More Information

[MicroTech 2021 Online Conference - 25 March 2021](#)

Heterogeneous Integration - Packaging Future Microsystems



For any other details or information please contact:

IMAPS-UK Secretariat
125 High Street Chesterton
Cambridge CB4 1NL UK
Tel: +44 0131 2029004
e-mail: Office@imaps.org.uk



The European Institute for the PCB Community

EIPC SPEeDNEWS

The Weekly On-Line Newsletter from the European Institute of Printed Circuits.

Issue 2- January 2020

ELECTRONICS INDUSTRY NEWS

PC Sales Remain on Fire as Fourth Quarter Shipments Grow 26.1% Over the Previous Year, According to IDC

With the pandemic still in full swing, traditional PCs (inclusive of desktops, notebooks, and workstations) were once again an in-demand consumer technology. The fourth quarter of 2020 (4Q20) saw global shipments grow 26.1% year over year to 91.6 million units, according to preliminary results from the International Data Corporation ([IDC](#)) [Worldwide Quarterly Personal Computing Device Tracker](#). The same category of devices grew 13.1% year over year for the full year 2020 with the catalysts being work from home, remote learning, and restored consumer demand.

"Every segment of the supply chain was stretched to its limits as production once again lagged behind demand during the quarter," said [Jitesh Ubrani](#) research manager for IDC's [Mobile Device Trackers](#). "Not only were PC makers and ODMs dealing with component and production capacity shortages, but logistics remained an issue as vendors were forced to resort to air freight, upping costs at the expense of reducing delivery times."

To put things into perspective, the last time the PC market saw annual growth of this magnitude was 2010 when the market grew 13.7%. A lot has changed in those ten years, including six years of PC market decline, as well as a year of flat growth. The question now is how long this resurgence will last.

"Demand is pushing the PC market forward and all signs indicate this surge still has a way to go," said [Ryan Reith](#), program vice president with IDC's [Worldwide Mobile Device Trackers](#). "The obvious drivers for last year's growth cantered around work from home and remote learning needs, but the strength of the consumer market should not be overlooked. We continue to see gaming PCs and monitor sales at all-time highs and Chrome-based devices are expanding beyond education into the consumer market. In retrospect, the pandemic not only fuelled PC market demand but also created opportunities that resulted in a market expansion."

Top 5 Companies, Worldwide Traditional PC Shipments, Market Share, and Year-Over-Year Growth, Q4 2020 (Preliminary results, shipments are in thousands of units)

Company	4Q20 Shipments	4Q20 Market Share	4Q19 Shipments	4Q19 Market Share	4Q20/4Q19 Growth
1. Lenovo	23,122	25.2%	17,918	24.7%	29.0%
2. HP Inc.	19,130	20.9%	17,185	23.7%	11.3%
3. Dell Technologies	15,797	17.2%	12,463	17.2%	26.8%
4. Apple	7,349	8.0%	4,927	6.8%	49.2%
5. Acer Group	6,551	7.2%	4,418	6.1%	48.3%
Others	19,641	21.4%	15,712	21.6%	25.0%
Total	91,590	100.0%	72,622	100.0%	26.1%

Source: IDC Quarterly Personal Computing Device Tracker, January 11, 2021

Top 5 Companies, Worldwide Traditional PC Shipments, Market Share, and Year-Over-Year Growth, Calendar Year 2020 (Preliminary results, shipments are in thousands of units)

Company	2020 Shipments	2020 Market Share	2019 Shipments	2019 Market Share	2020/2019 Growth
1. Lenovo	72,669	24.0%	64,855	24.2%	12.0%
2. HP Inc.	67,646	22.4%	62,935	23.5%	7.5%
3. Dell Technologies	50,298	16.6%	46,546	17.4%	8.1%
4. Apple	23,102	7.6%	17,894	6.7%	29.1%
5. Acer Group	20,989	6.9%	17,080	6.4%	22.9%
Others	67,901	22.4%	58,357	21.8%	16.4%
Total	302,605	100.0%	267,667	100.0%	13.1%

Source: IDC Quarterly Personal Computing Device Tracker, January 11, 2021

Notes:

- Some IDC estimates prior to financial earnings reports. Data for all companies are reported for calendar periods.
- Shipments include shipments to distribution channels or end users. OEM sales are counted under the company/brand under which they are sold.
- Traditional PCs include Desktops, Notebooks, and Workstations and do not include Tablets or x86 Servers. Detachable Tablets and Slate Tablets are part of the Personal Computing Device Tracker but are not addressed in this press release.

IDC's [Worldwide Quarterly Personal Computing Device Tracker](#) gathers detailed market data in over 90 countries. The research includes historical and forecast trend analysis among other data.

For more information, or to subscribe to the research, please contact Kathy Nagamine at 650-350-6423 or knagamine@idc.com.

The wonders of home schooling and home working – Ed,

Opinion: What CES 2021 says about our future

"The future has arrived---it's just not evenly distributed yet"

By [Bob O'Donnell](#) on January 12, 2021, 11:16 AM

Forward-looking: One of the most interesting and hopeful things about CES is that it paints a fascinating picture of how our future is supposed to look. Based on the first day of this year's "virtual" show, software-controlled bathtubs, cars with entertainment systems that rival our living rooms, foldable or rollable displays, 5G-controlled drones, and robots—of course—robots, apparently will all be part of our lives before we know it.

In reality, of course, these CES-driven future perspectives are typically driven by large companies' marketing departments describing potential futures that might be possible if we choose to believe their visions.

With the wisdom gained from having seen these visions come and go over the decades, I've learned that it rarely works out as cleanly and brilliantly as the images appear to be painted. Still, it's a great exercise to look through as much of the CES news flow as you can handle and try to make sense of what it all really means.

This year, a number of things spring to mind. First, perhaps to no one's surprise, there seems to be a lot more talking about big picture concepts and not nearly as much about specific products as we've seen in the past. To be clear, this isn't true in all areas—off the heels of a record-breaking year of growth, PC vendors and chip suppliers like Intel and AMD, in particular, cranked out a ton of new products for this year's show—but they were more of an exception.

The big press day before CES provided an interesting example of what I mean. None of the big press conferences ran more than 30 minutes and quite a few were less than 15 minutes long. Admittedly, some of this had to do with scheduling and the need to pre-record their news, but I found myself being surprised by how content-light even some of the biggest brands were during their time slots.

Many companies spent a great deal of time discussing big picture issues and topics like corporate social responsibility—all very important, to be clear—but not what we're used to seeing at CES. Toss in the fact that there are only about 1/3 as many companies participating in this year's show and the ability to interact with people from those companies is extremely limited, and well, it's just very different.

Second, the most interesting topics and most compelling visions seemed to be a bit further off than usual. Again, perhaps this shouldn't be surprising given where we are in the world, but very little of the coolest stuff is actually available for purchase—and honestly, I'm not convinced it's all things people really want anyway.

For example, several of the robots that Samsung showed off during its press conference garnered a great deal of interest—pour me a glass of wine and then put the dishes into the dishwasher—yes, please!—and were definitely impressive displays of technology, but they felt like something we won't really see commercially until at least the middle of the decade. Plus, I'm not convinced that many people are ready for these kinds of autonomous robots in

our homes just yet—it’s an awfully big leap from the company’s new AI-powered, JetBot 90 AI cleaning robot to the digital butler-like Bot Handy, but maybe that’s just me.

Also, the latest iterations of Harman’s ExP concept, which showed a car’s digital cockpit screen that moves up towards the driver and passenger—and lets you do things like gaming, experience virtual concerts, and even create your own songs or videos in the car—seems like an interesting idea that was taken a bit too far. I mean, I get the desire to make the experience of being in your car more comfortable, but do I really need to turn it into a place where I’m going to spend hours on end entertaining myself or working, particularly when we’re still years away from fully autonomous driving?



All of which takes me to my third and final point about this year’s CES.

Despite the big format change, the truth is, a majority of the most practical and relevant news from this year’s show (as, truthfully, it happens just about every year) is that we’re making slow, but steady progress in a number of areas about which many people do care.

Our TVs are getting bigger and the image quality is improving, thanks not only to display technologies like the Mini LEDs in Samsung’s new 110” offering but also AI, like the Cognitive Processor XR chip in Sony’s newest premium Bravia XR TVs, which uses intelligence to enhance the portions of an image where it believes people are focusing their attention.

We’re also seeing the opportunities that rollable screens can enable, including the expanding smartphone design from LG, as well as the roll-up tablet from TCL.

In addition, while people are interested in the concept of things like smart home, not all of it has to be overtly tech-oriented to make it appealing. At Kohler’s press event, for example, the company talked about several of its smart faucets and smart toilets that use sensors to function automatically, but don’t require voice-based interaction. To me, that’s an important example of recognizing that you can use technology to do clever things, but they can still be utterly intuitive and “tech-free” as well.

Conversely, the demonstration of Samsung’s latest version of its smart refrigerators tied to an online cooking class and grocery delivery service highlighted that sometimes it takes a lot more infrastructure and services to move from a clever gimmick to a truly useful device.

In the end, I can't help but be reminded of science fiction author William Gibson's famous quote from about a quarter of a century ago that "the future has arrived—it's just not evenly distributed yet".

As CES is showing us this year, and as it has in many years past, there is indeed some seed of truth in the big picture technology visions that companies portray at CES—it's just that you need to be incredibly wealthy to take advantage of all the best that tech has to offer today. For the rest of us, and for the companies that want to meet the more realistic visions to which we aspire in our homes, it's about figuring out what pieces of those future concepts are the most valuable and the most practical and making products that leverage them—for next year's CES.

Bob O'Donnell is the founder and chief analyst of [TECHanalysis Research, LLC](#) a technology consulting firm that provides strategic consulting and market research services to the technology industry and professional financial community. You can follow him on Twitter [@bobodtech](#).



The European Institute for the PCB Community

EIPC SPEeDNEWS

Issue 02 — January 2021

International Diary

2021

4th EIPC Technical Snapshot Webinar

Registrations via www.eipc.org

January 20

IPC APEX EXPO

March

San Diego, USA

EIPC @ SMTconnect

May 4-6

Nuremberg, Germany

5th EIPC Technical Snapshot Webinar

Registrations via www.eipc.org

February 17